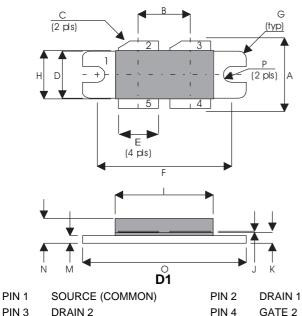
TetraFET

DMD5012 DMD5012-A

ROHS COMPLIANT METAL GATE RF SILICON FET

MECHANICAL DATA



PIN 3 DRAIN 2 GATE 1

E

PIN 5

DIM	Millimetres	Tol.	Inches	Tol.
А	15.24	0.50	0.600	0.020
В	10.80	0.13	0.425	0.005
С	45°	5°	45°	5°
D	9.78	0.13	0.385	0.005
Е	8.38	0.13	0.330	0.005
F	27.94	0.13	1.100	0.005
G	1.52R	0.13	0.060R	0.005
Н	10.16	0.15	0.400	0.006
Ι	21.84	0.23	0.860	0.009
J	0.10	0.02	0.004	0.001
Κ	1.96	0.13	0.077	0.005
М	1.02	0.13	0.040	0.005
Ν	4.45	0.38	0.175	0.015
0	34.04	0.13	1.340	0.005
Ρ	1.63R	0.13	0.064R	0.005

IMPROVED PERFORMANCE GOLD METALLISED SILICON DMOS RF FET 100W - 50V - 500MHz **PUSH-PULL**

FEATURES

- SUITABLE FOR BROAD BAND APPLICATIONS
- SIMPLE BIAS CIRCUITS
- ULTRA-LOW THERMAL RESISTANCE
- BeO FREE
- LOW Crss
- HIGH GAIN 15 dB MINIMUM

APPLICATIONS

 HF/VHF/UHF COMMUNICATIONS from 1 MHz to 500 MHz

P _D	Power Dissipation	500W (290W -A Version)
BV _{DSS}	Drain – Source Breakdown Voltage *	125V
BV _{GSS}	Gate – Source Breakdown Voltage *	±20V
I _{D(sat)}	Drain Current *	9A
T _{stg}	Storage Temperature	–65 to 150°C
Tj	Maximum Operating Junction Temperature	200°C

* Per Side

Semelab PIc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

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ELECTRICAL CHARACTERISTICS (T_{case} = 25°C unless otherwise stated)

	Parameter	Test C	onditions	Min.	Тур.	Max.	Unit
	PER SIDE						
BVpag	Drain–Source	V _{GS} = 0	I _D = 100mA	125			V
BV _{DSS}	Breakdown Voltage	VGS - 0	ID = 10011A	125			v
IDSS	Zero Gate Voltage	V _{DS} = 50V	$V_{GS} = 0$			3	mA
	Drain Current	VDS - 50 V				5	
I _{GSS}	Gate Leakage Current	$V_{GS} = 20V$	$V_{DS} = 0$			1	μA
V _{GS(th)}	Gate Threshold Voltage*	I _D = 10mA	$V_{DS} = V_{GS}$	1		7	V
9 _{fs}	Forward Transconductance*	V _{DS} = 10V	I _D = 3A	2.4			S
	TOTAL DEVICE						
G _{PS}	Common Source Power Gain	P _O = 100W		15			dB
η	Drain Efficiency	V _{DS} = 50V	I _{DQ} = 1.2A	65			%
VSWR	Load Mismatch Tolerance	f = 500MHz		20:1			—
PER SIDE							
C _{iss}	Input Capacitance	$V_{DS} = 50V V_{C}$	$_{SS} = -5V f = 1MHz$		100		pF
C _{oss}	Output Capacitance	$V_{DS} = 50V V_{C}$	GS = 0 f = 1MHz		45		pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 50V V_{C}$	$_{\rm SS} = 0$ f = 1MHz		1.5		pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle $\leq 2\%$

THERMAL DATA

R _{THj-case}	Thermal Resistance Junction – Case	Max. 0.35°C / W 0.6°C / W -A Version



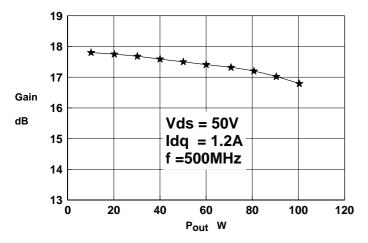
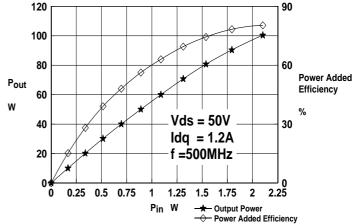
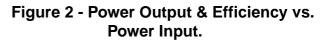


Figure 1 - Gain vs. Power Output.





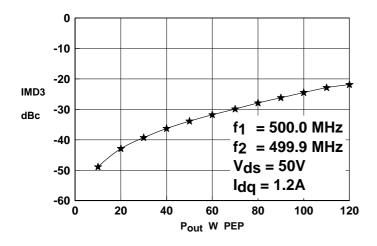


Figure 3 - IMD vs. Output Power.

DMD5012 OPTIMUM SOURCE AND LOAD IMPEDANCE

Frequency	Z _S	ZL	
MHz	Ω	Ω	
500	1.6 + j2.3	3.5 + j2.1	

N.B. Impedances measured terminal to terminal



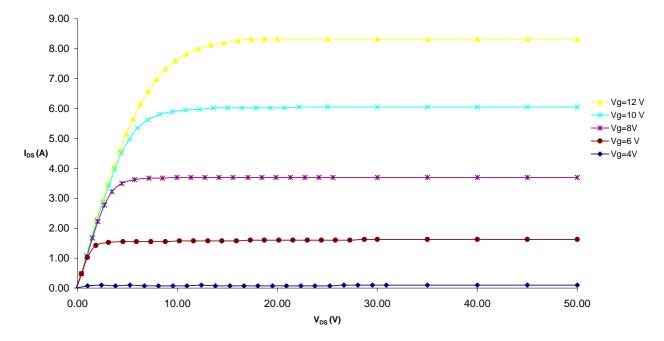
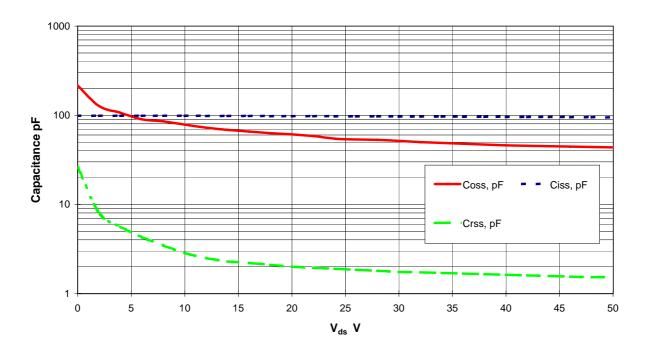
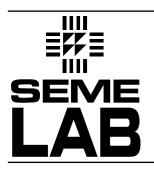
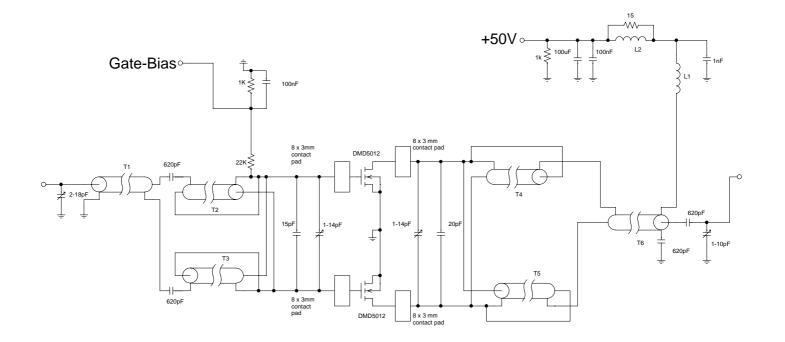


Figure 4 – Typical IV Characteristics.









DMD5012 500MHz TEST FIXTURE

T1,6	65mm	50 Ohm UT85 semi-rigid coax
T2,3,4,5	75mm	15 Ohm UT85-15 semi-rigid coax
L1	6 turns	21 swg enamelled copper wire, 3mm i.d.
L2	8.5 turns	19 swg enamelled copper wire on Fair-Rite FT82-43 core